

## ABSTRACT OF THE DISCLOSURE

A folded fin heat sink assembly and a method of fabricating a folded fin heat sink assembly for use as a cooling solution in micro-electronics and/or telecommunication applications. The heat sink assembly is formed by placing a sheet or paste of Sn-Zn solder upon a copper base plate, placing one or more aluminum folded fin assemblies on the solder sheet or paste, heating the base plate, the folded fin assembly and the solder to a temperature exceeding the liquidus temperature of the solder and allowing the solder to flow, and cooling the solder to form a soldered joint between the base plate and the folded fin assembly.

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37 38 39 40 41 42 43 44 45 46 47 48 49 50 51 52 53 54 55 56 57 58 59 60 61 62 63 64 65 66 67 68 69 70 71 72 73 74 75 76 77 78 79 80 81 82 83 84 85 86 87 88 89 90 91 92 93 94 95 96 97 98 99 100